

METHOD FOR MANUFACTURING PASSIVE OPTICAL COMPONENTS, AND
5 **DEVICES COMPRISING THE SAME**

Technical Field

10 The invention relates to the field of optics and more specifically to the manufacturing of optical and opto-electronic components. It relates to passive optical components and devices comprising these and to their manufacture. The invention relates to methods and
15 apparatuses according to the claims.

Background of the Invention

20 In US 2011/0043923 A1, a way is described, of how passive optical components can be manufactured by means of replication. E.g., the forming by replication of lenses as a unitary parts is described therein.

In US 2011/0050979 A1, an optical module for an electro-
25 optical device with a functional element is disclosed. In the manufacture of the module, lens elements are produced

on a transparent substrate. In order to ensure an improved performance of the functional element, an EMC shield is provided. E.g., the substrate can, on one of its surfaces, be provided with a layer of non-transparent, electrically
5 conductive material having apertures for the lens elements. The manufacture of a plurality of such modules on a wafer scale is also disclosed in US 2011/0050979 A1.

WO 2005/083789 A2 concerns a combination of passive optical elements with active optoelectronics. An optoelectronic
10 wafer comprising active optical components is provided with (micro-) optical structures, wherein the optical structures are allocated to the active optical components. The optical structures are manufactured using replication.

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Definition of Terms

"Active optical component": A light sensing or a light emitting component. E.g., a photodiode, an image sensor, an
20 LED, an OLED, a laser chip.

"Passive optical component": An optical component redirecting light by refraction and/or diffraction and/or reflection such as a lens, a prism, a mirror, or an optical system, wherein an optical system is a collection of such
25 optical components possibly also comprising mechanical elements such as aperture stops, image screens, holders.

"Opto-electronic module": A component in which at least one active and at least one passive optical component is comprised.

5 "Replication": A technique by means of which a given structure or a negative thereof is reproduced . E.g., etching, embossing, molding.

10 "Wafer": A substantially disk- or plate-like shaped item, its extension in one direction (z-direction or vertical direction) is small with respect to its extension in the other two directions (x- and y-directions or lateral directions). Usually, on a (non-blank) wafer, a plurality of like structures or items are arranged or provided therein, typically on a rectangular grid. A wafer may have opening or holes, and a wafer may even be free of material
15 in a predominant portion of its lateral area. Although in many contexts, a wafer is understood to be prevailingly made of a semiconductor material, in the present patent application, this is explicitly not a limitation.

20 Accordingly, a wafer may prevailingly be made of, e.g., a semiconductor material, a polymer material, a composite material comprising metals and polymers or polymers and glass materials. In particular, hardenable materials such as thermally or UV-curable polymers are interesting wafer materials in conjunction with the presented invention.

25 "Lateral": cf. "Wafer"

"Vertical": cf. "Wafer"

"Light": Most generally electromagnetic radiation; more particularly electromagnetic radiation of the infrared, visible or ultraviolet portion of the electromagnetic spectrum.

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Summary of the Invention

One object of the invention is to create an improved way of
10 manufacturing passive optical components and devices
comprising at least one such passive optical component.
More generally, a device and methods for manufacturing a
device are claimed, wherein the device comprises at least
one optics member and at least one passive optical
15 component, respectively, and it should be noted that said
device and said passive optical component, respectively,
can be identical with said device and said passive optical
component, respectively, itself.

Another object of the invention is to provide a relatively
20 simple way of manufacturing such devices and to provide
corresponding devices.

Another object of the invention is to provide a way of
manufacturing such devices, in particular in large numbers,
that has a particularly small number of manufacturing steps
25 and to provide corresponding devices.

Another object of the invention is to provide a
particularly efficient way of manufacturing such devices

and to provide corresponding devices. In particular, the assembly shall be particularly efficient.

Another object of the invention is to provide a particularly cost-effective way of manufacturing such
5 devices and to provide corresponding devices. In particular, the assembly shall be particularly cost-effective.

Another object of the invention is to provide a particularly time-saving way of manufacturing such devices
10 and to provide corresponding devices.

Another object of the invention is to provide devices of particularly small outer dimensions and to provide corresponding manufacturing methods.

Another object of the invention is to provide devices
15 having a particularly high level of integration and to provide corresponding manufacturing methods.

Another object of the invention is to provide devices consisting of a particularly small number of constituents and to provide corresponding manufacturing methods.

20 Another object of the invention is to provide devices having a particularly accurate relative positioning of individual optical components comprised in the device and to provide corresponding manufacturing methods.

Another object of the invention is to provide devices
25 having particularly good optical properties and to provide corresponding manufacturing methods.

Further objects emerge from the description and embodiments below.

At least one of these objects is at least partially achieved by devices and methods according to the patent claims.

The method for manufacturing a device comprising at least
5 one passive optical component comprises the step of

a) providing a wafer comprising at least one blocking portion and a multitude of transparent elements;

wherein each of said multitude of transparent elements is made of material substantially transparent for light of at
10 least a specific spectral range, referred to as transparent material, and said at least one blocking portion is made of material substantially non-transparent for light of said specific spectral range, referred to as non-transparent material.

15 This can be useful in many aspects and applications and devices, as will be become clear from the text below. E.g., an efficient manufacturing of passive optical components on wafer level can be accomplished this way, in particular wherein at least a portion of the passive optical
20 components (in particular optical structures as described further below) extends vertically beyond the vertical extension of the surrounding wafer portions, the surrounding wafer portions being usually formed by the blocking portion.

25 Typically, said device comprises at least a portion of said wafer.

Typical lateral dimensions of said wafer are at least 5 cm or 10 cm, and up to 30 cm or 40 cm or even 50 cm; typical

vertical dimensions are at least 0.2 mm or 0.4 mm or even 1 mm, and up to 6 mm or 10 mm or even 20 mm.

Usually, said passive optical component is provided for influencing, in particular for guiding light.

- 5 In one embodiment, each of said multitude of transparent elements is laterally adjacent to said at least one blocking portion.

In one embodiment which may be combined with the before-addressed embodiment, each of said multitude of transparent
10 elements is laterally encircled by said at least one blocking portion.

In one embodiment which may be combined with one or more of the before-addressed embodiments, said at least one blocking area is made substantially of exactly one non-
15 transparent material.

In one embodiment which may be combined with one or more of the before-addressed embodiments, a vertical extension of each of said multitude of transparent elements is at least approximately equal to a vertical extension of said at
20 least one blocking portion.

In one embodiment which may be combined with one or more of the before-addressed embodiments, each of said multitude of transparent elements has two opposing at least approximately flat surfaces substantially perpendicular to
25 a vertical direction.

In one embodiment which may be combined with one or more of the before-addressed embodiments, the method comprises the step of

d) manufacturing said wafer;

wherein step d) comprises the steps of

5 d1) providing a precursor wafer substantially made of
said non-transparent material having openings in
places where said transparent elements are
supposed to be located;

 d2) at least partially filling said openings with at
least one of said transparent materials.

10 This can be a particularly efficient way of manufacturing
said wafer.

In one embodiment referring to the before-addressed
embodiment, during step d2), said transparent materials are
in a liquid or viscous state, and wherein subsequent to
step d2), the step of

15 d3) hardening said transparent material;

is carried out. In particular, said hardening comprises
curing.

In one embodiment referring to one or both of the two
before-addressed embodiments comprising steps d1) and d2),
20 step d2) is carried out using a dispenser. Therein, one or
several of said openings can be filled at a time.

An alternative to using a dispenser is using a squeegee
process, e.g., like used in a screen-printing process.

25 In one embodiment referring to one or more of the before-
addressed embodiments comprising steps d1) and d2), the
method comprises the step of manufacturing said precursor
wafer using replication. This can be very efficient. When a

hardening step is carried out during said replication,
e.g., a curing step, this will rather be done by heating,
because a non-transparency of the non-transparent material
of the blocking portion may in many cases be accompanied by
5 a non-transparency for radiation that would be used for
accomplishing radiation hardening.

An alternative to replication is creating said openings by
means of drilling or etching, or to manufacture the
precursor wafer using molding. If molding is used,
10 duroplastic injection molding can be a particularly
suitable method for various applications.

In one embodiment which may be combined with one or more of
the before-addressed embodiments, the method comprises the
step of

- 15 c) manufacturing a wafer referred to as optics wafer,
comprising a multitude of passive optical components
comprising said at least one passive optical
component;

wherein step c) comprises the step of

- 20 c1) producing said multitude of passive optical
components by producing on each of said multitude
of transparent elements at least one optical
structure.

Usually, said at least one optical structure is provided
25 for influencing, in particular for guiding light more
particularly for redirecting light.

It is possible to provide that said device is or comprises
said optics wafer or comprises a portion thereof.

In one embodiment referring to the before-addressed embodiment (comprising steps c) and c1)), said at least one optical structure comprises at least one lens element.

This is a typical application. Said lens element is usually
5 a lens being a constituent of a composed lens comprising in addition at least one of said transparent elements.

The lens element itself and a composed lens as mentioned before can work based on refraction and/or on diffraction.

Instead of a lens element (or in addition thereto), other
10 elements such as a prism element may be comprised in the optical structure. And coated elements may be suitable, too, e.g., a transparent part coated with a reflective coating, serving as a mirror element.

In one embodiment referring to one or more of the before-
15 addressed embodiments comprising steps c) and c1)), said producing said optical structures (mentioned in step c1)) is carried out using replication. This is a very efficient and precise way of producing said optical structures.

Usually, a replication material used for said replication
20 is substantially transparent for light of said specific spectral range (at least when the replication material is in a hardened state). A way of carrying out the replication suitable for many applications comprises embossing.

In one embodiment referring to the before-addressed
25 embodiment, said producing said optical structures using replication comprises the steps of

r1) applying a replication material to each of said
multitude of transparent elements;

r2) replicating a structured surface in said replication material;

r3) hardening said replication material;

r4) removing said structured surface.

5 Usually, the steps r1) to r4) are subsequently carried out in the cited order or in the order r2, r1, r3, r4.

Replication material is a hardenable, typically curable material; in particular hardenable and curable, respectively, using ultraviolet radiation or heating.

10 Suitable replication materials can be, e.g., polymers such as epoxy resins.

It is possible to provide that said producing said optical structure using replication is carried out in one replication process simultaneously for all of said optical
15 structures. But it is also possible to provide that said producing said optical structures using replication is carried out by subsequently carrying out a multitude of replication processes, typically one replication process for each of said optical structures, but possibly one
20 single replication process for a fraction of all of said optical structures.

In one embodiment referring to the before-addressed embodiment comprising steps r1) to r4), said replicating mentioned in step r2) is carried out in an aligned manner;
25 more specifically such that said structured surface is aligned in a well-defined manner with respect to at least one of said multitude of transparent elements.

In one embodiment referring to one or more of the before-addressed embodiments comprising steps c) and c1), the method comprises the step of

5 e) preparing a wafer stack comprising said optics wafer and at least one additional wafer;

f) obtaining a multitude of separate modules each comprising at least one of said multitude of passive optical components, by separating said wafer stack.

In one embodiment referring to the before-addressed
10 embodiment (comprising steps e) and f)), step e) comprises fixing, in particular bonding the wafers of said wafer stack with respect to each other, e.g., by gluing, e.g., using a heat-curable epoxy resin.

In one embodiment referring to one or more of the before-
15 addressed embodiments comprising steps e) and f)), step e) comprises aligning the wafers of said wafer stack with respect to each other, in particular in such a way that they are suitably aligned when fixing them with respect to each other.

20 In one embodiment which may be combined with one or more of the before-addressed embodiments comprising steps e) and f), at least one of said additional wafers comprises a multitude of active optical components, said separate modules each comprising at least one of said multitude of
25 active optical components. Therein, usually, each of said transparent elements and passive optical components, respectively, is allocated with at least one of said multitude of active optical components; and this is usually

provided for during manufacturing by aligning said wafer accordingly.

In one embodiment which may be combined with one or more of the before-addressed embodiments comprising steps e)

5 and f), at least one of said additional wafers is a spacer wafer structured and configured for providing a well-defined vertical distance between said passive optical components and mechanical stops provided by said spacer wafer.

10 It is possible to provide that said device is or comprises said wafer stack or comprises a portion thereof.

It is possible to provide that said device is or comprises one or at least one of said modules.

In addition to the method addressed above, the invention
15 also comprises a device:

The device comprises at least one optics member comprising at least one transparent portion and at least one blocking portion, wherein

20 said at least one transparent portion is made of one or more materials substantially transparent for light of at least a specific spectral range, referred to as transparent materials, and said at least one blocking portion is made of one or more materials substantially non-transparent for light of said specific spectral
25 range, referred to as non-transparent materials, said transparent portion comprises at least one passive optical component,

said at least one passive optical component comprises
a transparent element having two opposing at least
approximately flat surfaces substantially
perpendicular to a vertical direction, and, attached
5 to said transparent element, at least one optical
structure.

The invention comprises devices with features of
corresponding methods according to the invention, and, vice
versa, also methods with features of corresponding devices
10 according to the invention.

The advantages of the devices basically correspond to the
advantages of corresponding methods, and, vice versa, the
advantages of the methods basically correspond to the
advantages of corresponding devices.

15 In one embodiment, said transparent element is a unitary
part.

In one embodiment which may be combined with the before-
addressed embodiment, said passive optical component is not
a unitary part. It comprises at least two constituents,
20 usually two or three constituents. These are usually said
transparent element and said at least one optical
structure.

In one embodiment which may be combined with one or more of
the before-addressed device embodiments, said two opposing
25 at least approximately flat surfaces are arranged in a
distance at least approximately equal to a thickness of
said at least one blocking portion measured along said
vertical direction.

In one embodiment which may be combined with one or more of the before-addressed device embodiments, each constituent of each of said transparent portions is made of one (single) transparent material, wherein these can be
5 identical or different for one of more of the constituents of each of said transparent portions.

In one embodiment which may be combined with one or more of the before-addressed device embodiments, said at least one transparent portion is identical with said at least one
10 passive optical component.

In one embodiment which may be combined with one or more of the before-addressed device embodiments, said optics member without said at least one optical structure is generally planar.

15 In one embodiment which may be combined with one or more of the before-addressed device embodiments, said optics member without said at least one optical structure is of generally block- or plate-like shape.

It is possible to provide that the device is one such
20 optics members.

In one embodiment which may be combined with one or more of the before-addressed device embodiments, said at least one blocking portion is made of a hardened hardenable material, in particular of a cured curable material.

25 In one embodiment which may be combined with one or more of the before-addressed device embodiments, said at least one blocking portion is manufactured using replication. An alternative method would be to start from a blank wafer and

use drilling or etching, or to use molding for manufacturing the at least one blocking portion.

In one embodiment which may be combined with one or more of the before-addressed device embodiments, said transparent
5 element is made of a hardened hardenable material, in particular of a cured curable material. If said transparent element is manufactured using dispensing, a hardened hardenable dispensable material will usually be used. If
10 said transparent element is manufactured using a squeegee process, a hardened hardenable material applicable in a squeegee process will usually be used.

In one embodiment which may be combined with one or more of the before-addressed device embodiments, said at least one optical structure is made of a hardened hardenable
15 material, in particular of a cured curable material.

In one embodiment which may be combined with one or more of the before-addressed device embodiments, said passive optical component comprises at least one optical structure attached to each of said opposing surfaces, in particular,
20 it comprises exactly one optical structure per opposing surface.

In one embodiment which may be combined with one or more of the before-addressed device embodiments, the device comprises an opto-electronic module in which said at least
25 one optics member is comprised.

In one embodiment referring to the before-addressed embodiment, said opto-electronic module comprises at least one active optical component, in particular wherein in said opto-electronic module, said at least one active optical

component and said at least one optics member are fixed with respect to one another. For example, said opto-electronic module can be a packaged component.

5 In one embodiment referring to one or both of the two last-addressed embodiments, said device is said opto-electronic module.

10 In one embodiment which may be combined with one or more of the before-addressed device embodiments comprising said opto-electronic module, the device comprises a printed circuit board on which said opto-electronic module is mounted. In particular, wherein said device is an electronic device.

15 In one embodiment which may be combined with one or more of the before-addressed device embodiments, the device comprises a wafer referred to as optics wafer, said optics wafer comprising a multitude of said optics members, in particular wherein said optics members are arranged (laterally) next to one another.

20 It is possible to provide that said device is or comprises said optics wafer.

In one embodiment referring to the before-addressed embodiment, the device comprises a wafer stack in which said optics wafer is comprised. It is possible to provide that said device is or comprises said wafer stack.

25 In one embodiment which may be combined with one or more of the before-addressed device embodiments comprising said opto-electronic module, the device comprises a wafer stack in which a multitude of said opto-electronic modules is

comprised, in particular wherein said oopto-electronic modules are arranged (laterally) next to one another. It is possible to provide that said device is or comprises said wafer stack.

5 Further embodiments and advantages emerge from the dependent claims and the figures.

Brief Description of the Drawings

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Below, the invention is described in more detail by means of examples and the included drawings. The figures show schematically:

15

Fig. 1 a diagrammatical illustration of a cross-section through a device being a passive optical component;

Fig. 2 a diagrammatical illustration of a top view of the device of Fig. 1;

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Fig. 3 a diagrammatical illustration of a manufacturing step in a cross-sectional view;

Fig. 4 a diagrammatical illustration of a manufacturing step in a cross-sectional view;

Fig. 5 a diagrammatical illustration of a manufacturing step in a cross-sectional view;

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Fig. 6 a diagrammatical illustration of a cross-section through a device being an optics wafer;

- Fig. 7 a diagrammatical illustration of a cross-section
through a device being an optics wafer;
- Fig. 8 a diagrammatical illustration of a cross-section
illustrating a manufacturing step;
- 5 Fig. 9 a diagrammatical illustration of a cross-section
illustrating a manufacturing step;
- Fig. 10 a diagrammatical illustration of a detail of a
cross-sectional view;
- Fig. 11 a diagrammatical illustration of a detail of a
10 cross-sectional view;
- Fig. 12 a diagrammatical illustration of a cross-section
through a device being an opto-electronic module
illustrating a device being an electronic device;
- Fig. 13 a cross-sectional view of wafers for forming a
15 wafer stack for manufacturing a multitude of
modules of Fig. 12;
- Fig. 14 a cross-sectional view of a device being a wafer
stack for manufacturing a multitude of modules of
Fig. 12;
- 20 Fig. 15 a diagrammatical illustration of a cross-section
through a device being a semi-finished part;
- Fig. 16 a diagrammatical illustration of a cross-section
through a device being a semi-finished part.

The reference symbols used in the figures and their meaning
25 are summarized in the list of reference symbols. The
described embodiments are meant as examples and shall not
confine the invention.

Detailed Description of the Invention

5 Fig. 1 is a schematized diagrammatical illustration of a cross-section through a device being a passive optical component O. Fig. 2 is a schematized diagrammatical illustration of a top view of the device of Fig. 1. Passive optical component O can and will also be referred to as
10 optics member O.

In Fig. 1, the vertical (z) direction is indicated, as well as the x direction. The directions indicated in Fig. 2 (directions in the x-y plane) are referred to as lateral directions.

15 Optics member O comprises a blocking portion b and two transparent portions t. In fact: Optics member O consists of a blocking portion b and two transparent portions t. Blocking portion b is made of a material, typically a polymer material, which is substantially non-transparent
20 for light of a specific spectral range (wavelength or wavelength range), whereas the transparent portions t are made of a material which is substantially transparent for light at least of said specific spectral range. This way, blocking portion b functions as an aperture for each of the
25 transparent portions t and also fixes (or holds) the transparent portions t. And, as will become clearer later (cf. Fig. 12), blocking area b can function as a shield for protection from undesired light, by substantially

attenuating or blocking light of said specific spectral range.

Each of the transparent portions t comprises at least two parts; in the example of Figs. 1 and 2, it is three parts:

5 Two lens elements 5 (or, more generally: optical structures 5) and a transparent element 6. Together, these form a lens member L (or, more generally: a passive optical component). Optical structures 5 protrude from the surface described by the blocking portion b ; in other words, they
10 extend vertically beyond the level described by the blocking portion b . When the optical structures 5 are lens elements (e.g., concave ones or, as shown in Fig. 1, convex ones) having at least one apex, these apices are located outside a vertical cross-section of the optics member O
15 (Fig. 1).

Blocking portion b together with transparent elements 6 describes a (close-to-perfect) solid plate-like shape. The optical structures 5 protrude therefrom. Each of the transparent elements 6 has two opposing lateral surfaces
20 which are substantially flat, i.e. two surfaces lying substantially in the x - y plane.

The outer shape of optics member O is generally plate- or disk-like, with rectangular side walls.

Particularly interesting is the manufacturability of the
25 optics members O and of other devices according to the invention. In particular, wafer-level manufacturing is possible. This will be explained referring to Figs. 3 to 14.

Figs. 3 to 7 are schematized diagrammatical illustrations of manufacturing steps, in a cross-sectional view. Fig. 3 illustrates schematically a precursor wafer 8 made of non-transparent material, having a multitude of holes or openings 11. One or more of these are typically arranged on a rectangular lattice; since optics member 0 of Figs. 1 and 2 to be manufactured comprises two transparent portions t, these two are arranged on a rectangular lattice.

10 Precursor wafer 8 can be manufactured by replication, e.g., using embossing or molding. Or a blank wafer can be provided with the openings 11 by drilling or etching.

It is to be noted that the shape of the openings 11 in precursor wafer 8 can of course be different from the cylindrical shape shown in Figs. 1 to 3. The holes 11 need not be prismatic having a vertical axis, and a lateral cross-section does not have to be circular. E.g., elliptic shapes are possible; and the shape in a lateral cross-section may vary along the vertical direction; and the area described by the holes 11 in a lateral cross-section may vary along the vertical direction.

In a next step (cf. Fig. 4), the transparent elements 6 are formed by filling the openings 11 with a suitable transparent material T. During the filling, the transparent material T, typically a polymer, is liquid or viscous. A squeegee process similar to what is known from screen printing can be used, or a dispenser, e.g., like known from semiconductor industry and used for underfilling, can be used. The dispensing can be carried out one-by-one, or

several openings are simultaneously filled, e.g., by using several hollow needles outputting transparent material T.

During the filling, the precursor wafer 8 lies on a support layer 12, e.g., made of a silicone such as

5 polydimethylsiloxane. Support layer 12 is supported by a rigid support substrate 13, e.g., a glass plate, for mechanical stability.

During filling-in the transparent material T, care has to be taken order to prevent the formation of air bubbles or
10 cavities in the material T, because this would likely degrade the optical properties of the passive optical components L to be produced, since transparent element 6 is a constituent thereof. E.g., one can carry out the dispensing in such a way that wetting of the wafer material
15 starts at an edge formed by the precursor wafer 8 and the underlying support layer 12 or in a place close to such an edge; e.g., by suitably guiding a hollow needle outputting the material T close to such an edge. This is visualized in Figs. 8 and 9 which are schematized diagrammatical
20 illustrations of a cross-section for illustrating this manufacturing step. Depending on properties of the involved materials, more particularly of the surface tensions of transparent material T, of the material of precursor wafer 8 and of the material of support layer 13, the shapes
25 described by the material T while being filled in into the holes 11 can vary and possibly look similar to what is schematically illustrated in Fig. 8 and in Fig. 9, respectively. The dashed lines indicate the time evolvement of the shape with increasing amount of filled-in material

T, Figs. 8 and 9 illustrating different behavior for different wetting angles.

The filling-in is stopped when enough material T is filled in. Before proceeding, the filled-in transparent material T
5 is hardened, e.g., by curing it, e.g., using heat or UV radiation. It is possible, that the so-obtained transparent elements have two (nearly) perfectly planar lateral surfaces, in particular (nearly) perfectly forming a common planar surface with the surrounding (blocking) portion of
10 the precursor wafer 8. But possibly, the filling, accomplished using a squeegee or by dispensing or accomplished differently, may be less perfect. Examples therefor are shown in Figs. 10 and 11, which are schematized diagrammatical illustrations of a detail of a
15 cross-sectional view. E.g., a concave surface might be formed as illustrated in Fig. 10, or a convex surface might be formed as illustrated in Fig. 11. In the convex case, it can be advantageous to provide a polishing step before continuing with the next manufacturing steps. By means of
20 the polishing, it is possible to achieve that the protruding portion is taken down at least partially. In addition, it is possible that polishing can remove spilled-over transparent material, i.e. material which has not been deposited in the desired location during filling-in, e.g.,
25 material that has not been deposited on a transparent element, but, e.g., slightly next thereto.

It is alternatively also possible to accomplish the formation of the transparent elements 6 in a different fashion involving finishing steps or not. By means of the

support layer 12, it can be possible to ensure a rather planar surface of the transparent material T at that side of the wafer, but other ways of accomplishing this might also be used.

5 When each of the openings 11 contains an appropriate amount of hardened transparent material T, optical structures 5 are applied thereto (cf. Figs. 5 and 6). This can be accomplished, e.g., by replication, in a way known in the art, e.g., as described in WO 2005/083789 A2 or in
10 US 2011/0050979 A1. E.g., in a form having a structured surface describing a negative of the optical structures 5 to be produced, a suitable amount of a replication material provided, and then, the form with the structured surface is moved towards the wafer, so as to get the replication
15 material in an appropriate contact with a transparent element 6. Subsequently, the replication material is hardened, e.g., cured, e.g., by heating or irradiating with light (such as UV light), and the form is removed. The formation of the optical structures 5 (by replication or
20 differently) may be accomplished one-by-one or several at a time (but only a fraction of all on one side the wafer), or simultaneously for all on one side of the wafer.

The optical structures 5 can be formed on one or on both sides of the wafer (cf. Figs. 5 and 6). The lateral
25 extension of the optical structures 5 can be larger or smaller than the lateral extension of the transparent elements 6, or substantially be identical, as shown in Figs. 5 and 6. The optical structures 5 can be lens elements of virtually any shape, be it refractive and/or

diffractive lens elements, or prism elements or others. For many applications, lens elements are a suitable choice.

The so-obtained optics wafer OW (cf. Fig. 6) can be a device itself and can be used, e.g., for producing further
5 products.

It is also possible to separate such an optics wafer OW into a multitude of optics member like those shown in Figs. 1 and 2, e.g., by dicing. In Fig. 7 showing a schematized diagrammatical illustration of a cross-section
10 through a device being an optics wafer OW, the thin dashed rectangles indicate where separation can take place.

Fig. 12 is a schematized diagrammatical illustration of a cross-section through a device being an opto-electronic module 1 also illustrating a device being an electronic
15 device 10 comprising such an opto-electronic module 1 mounted on a printed circuit board 9 of the electronic device 10. The electronic device 10 can be, e.g., a hand-held electronic communication device such as a smart phone, or a photographic device such as a photo camera or a video
20 camera.

The opto-electronic module 1 comprises an optics member O as shown in Figs. 1 and 2 and also at least one active optical component such as a detector D (e.g., a photo diode) and a light emitter E (e.g., a light-emitting
25 diode). The active optical components D, E are mounted on a substrate P provided with solder balls 7. Between substrate P and optics member O, a separation member S (or spacer member S) with openings 4 is arranged, i.a. for ensuring a suitable distance between the active optical

components D, E and the passive optical components L. On top, a baffle member B having transparent regions 3 is arranged functioning as a baffle.

Said substrate P, said optics member O, said baffle member B and said separating member S are of generally block- or plate-like shape (wherein at least said separating member S and said baffle member B have at least one hole each). This way, it is possible that a particularly good manufacturability is achieved.

10 There exists a specific wavelength range for which the passive optical components L and thus the transparent material T and the material of which the optical structures 5 are made (which may be identical with or different from material T) are transparent, but for which the material of 15 which the blocking portion b is made is non-transparent.

There is, e.g., if the opto-electronic module 1 is a proximity sensor, an overlapping wavelength range of the wavelength range of light emittable by light emitter E and the wavelength range of light detectable by the light 20 detector D. At least in that overlapping wavelength range, blocking portion b will be non-transparent, and at least in a portion of said overlapping wavelength range, transparent portion t will be transparent. Note that the term wavelength range does not imply that it is contiguous. Said 25 overlapping wavelength range can be in the infrared portion and more specifically in the near-infrared portion of the electromagnetic spectrum. This can be particularly useful for proximity sensor.

An opto-electronic module 1 as shown in Fig. 12 can well be manufactured on wafer-scale. Therein, optics wafers like shown in Fig. 6 can be used.

Fig. 13 is a schematized cross-sectional view of wafers for forming a wafer stack 2 (cf. Fig. 14) for manufacturing a multitude of modules 1 of Fig. 12.

Four wafers are sufficient for manufacturing a multitude of modules 1 as shown in Fig. 12: A substrate wafer PW, a spacer wafer SW, an optics wafer OW (like shown in Fig. 6) and a baffle wafer BW. Each wafer comprises a multitude of the corresponding members comprised in the corresponding module 1 (cf. Fig. 12), usually arranged on a rectangular lattice, typically with a little distance from each other for a wafer separation step.

Substrate wafer PW can be a printed circuit board (PCB) of standard PCB materials, provided with solder balls 7 on the one side and with active optical components (E and D) soldered to the other side. The latter can be placed on substrate wafer PW by pick-and-place using standard pick-and-place machines.

Ways of manufacturing optics wafer OW have been described above.

In order to provide maximum protection from detecting undesired light, all wafers PW, SW, OW, BW can substantially be made of a material substantially non-transparent for light detectable by detecting members D, of course except for transparent portions t and transparent regions 3.

Wafers SW and BW and possibly also all or a portion of wafer OW can be produced by replication. In an exemplary replication process which can also be used for manufacturing precursor wafer 8 or transparent elements 6,
5 a structured surface is embossed into a liquid, viscous or plastically deformable material, then the material is hardened, e.g., by curing using ultraviolet radiation or heating, and then the structured surface is removed. Thus, a replica (which in this case is a negative replica) of the
10 structured surface is obtained. Suitable materials for replication are, e.g., hardenable (more particularly curable) polymer materials or other replication materials, i.e. materials which are transformable in a hardening step (more particularly in a curing step) from a liquid, viscous
15 or plastically deformable state into a solid state. Replication is a known technique, cf., e.g., WO 2005/083789 A2 or US 2011/0050979 A1 for more details about this.

Fig. 14 is a schematized cross-sectional view of a device
20 being a wafer stack 2 for manufacturing a multitude of modules 1 of Fig. 12.

In order to form a wafer stack 2, the wafers BW, OW, SW, PW are aligned and glued together, e.g., using a heat-curable epoxy resin. The aligning comprises aligning said substrate
25 wafer PW and said optics wafer OW such that each of said detecting members D is aligned with respect to at least one of said transparent portions t, in particular wherein each of said detecting members D is aligned in the same way to

one of said transparent portions t each, and the same applies to the light emitters E .

The thin dashed rectangles indicate where separation takes place, e.g., by means of a dicing saw.

5 Although Figs. 3 to 7 and 13 and 14 only show provisions for three modules 1, there will usually be in one wafer stack provisions for at least 10, rather at least 30 or even more than 50 modules in each lateral direction.

It is to be noted that it is possible to think of devices
10 which comprise an optics member O , wherein the optics member is not comprised in an opto-electronic module 1.

It is further to be noted that the passive optical components L obtained in a manner described above are not unitary parts. They comprise at least two, usually two or
15 three constituents, namely transparent element 6 and optical structures 5 attached thereto. Transparent element 6, however, usually is a unitary part.

A semi-finished part (which can in a certain view also be a device according to the invention) obtained by providing
20 the transparent elements 6 in a precursor wafer 8 usually is a flat disk-like wafer having no holes penetrating the wafer (or at least no holes penetrating the wafer in the regions where the transparent portions t are).

The semi-finished part can have virtually no or only
25 shallow surface corrugations in those regions, wherein such surface corrugations, if present, are usually concave (cf. Fig. 10), i.e. do not extend beyond the wafer surface as described by the at least one blocking portion b . Convex

meniscuses possibly formed can be flattened, e.g., as described above, by polishing, so as to obtain a transparent element 6 having parallel surfaces adjusted to the wafer thickness, wherein possibly also the wafer
5 thickness can be adjusted (reduced).

But: The semi-finished part can alternatively have a structured surface, on one or on both sides, in particular in those regions where the transparent portions t are. There can be wanted corrugations in blocking portion b. In
10 particular, it is possible that a wafer, a "combined optics wafer", is provided which is a combination of an optics wafer (such as the described optics wafer OW) and a spacer wafer (such as the described spacer wafer SW). Accordingly, then, the spacer wafer is optional, its properties and
15 functions are fulfilled by an optics wafer ("combined optics wafer") structured and configured accordingly. This can be accomplished, e.g., by manufacturing as a unitary part: what is described above as spacer wafer SW and what is described above as at least one blocking portion b. A
20 corresponding optics wafer ("combined optics wafer") can be readily visualized when looking upon wafers OW and SW in Fig. 14 as one single part. Starting from a suitable semi-finished part, a "combined semi-finished part", a "combined optics wafer" can be obtained by producing thereon (on
25 transparent portions of the "combined semi-finished part") optical structures, e.g., in a way as described above, e.g., by dispensing.

Another example of a "combined semi-finished part" (referenced ow') is illustrated in Fig. 16, whereas a semi-

finished part ow which more closely corresponds to what is described in conjunction with Figs. 3 to 7 and 12 to 14 is illustrated in Fig. 15.

Furthermore an optics wafer ("combined optics wafer") can
5 be provided which is a combination of an optics wafer (such as the described optics wafer OW) and a baffle wafer (such as the described baffle wafer BW). Accordingly, then, the baffle wafer is optional, its properties and functions are fulfilled by an optics wafer ("combined optics wafer")
10 which is structured and configured accordingly. This can be accomplished, e.g., by manufacturing as a unitary part: what is described above as baffle wafer BW and what is described above as at least one blocking portion b. A corresponding optics wafer can be readily visualized when
15 looking upon wafers OW and BW in Fig. 14 as one single part. A suitable "combined semi-finished part" might look similar to what is shown in Fig. 16.

Of course, it is also possible that both sides of an optics wafer ("combined optics wafer") are structured. E.g., so as
20 to make, in the embodiment of Fig. 14, baffle wafer BW and spacer wafer SW obsolete.

Filling-in of transparent material T into a single- or both-sidedly structured precursor wafer for forming the transparent elements 6 (for obtaining a semi-finished part)
25 can be accomplished similarly to what is shown in Fig. 4 (and what is implied in Fig. 16 by the support layer 12), wherein in Fig. 16, a not-structured side of "combined semi-finished part" ow' faces the support layer 12. Alternatively, a structured support layer 12 could be used

during forming the transparent elements 6, for avoiding a (too intense) flowing-through of filled-in material through the openings of the precursor wafer. The latter was of proceeding can be particularly useful when a precursor
5 wafer having a structured surface on both sides shall be provided with the transparent elements 6.

Corresponding to what has just been described for wafers, a "combined optics member" can also be provided. The blocking portion of an optics member can have a structured surface,
10 in particular a surface with protruding portions protruding vertically beyond a surface of a transparent element of the "combined optics member". It is possible that a member ("combined optics member") is provided which is a combination of the above-described optics member and the
15 above-described separation member (or a combination of the described optics member and the described baffle member, or a combination of all three). Accordingly, then, the separation member (and/or the baffle member) is optional, its properties and functions are fulfilled by an optics
20 member which is structured and configured accordingly. This can be accomplished, e.g., by manufacturing as a unitary part: what is described above as separation member S (and/or what is described above as baffle member B) and what is described above as at least one blocking portion b.
25 A usual consequence of providing such a "combined optics member" or "combined optics wafer" is that the number of parts (of an item to be constructed, such as of a module 1) and the number of assembly steps is reduced, and less aligning errors will usually occur.

Coming back to Fig. 15, the semi-finished part now shown there can be subjected to a polishing step on one or on both sides. The polishing step can be accomplished, e.g., for thinning the wafer now (precisely) to a desired
5 thickness, and/or for improving the optical properties (at least of the transparent elements 6). Of course, also a one-sidedly structured semi-finished part can be polished, at least on its flat (not-structured) side.

Furthermore, it is to be noted that it is possible to
10 polish precursor wafers, on one or both sides, at least on at least one flat side. Doing so not only possibly contributes to a flatter and/or more even surface of the precursor wafer, but may allow to reduce the thickness of the precursor wafer to a desired thickness, which may be
15 helpful in possible subsequent manufacturing steps.

If a semi-finished part ("combined" or not) is itself a device and shall be used without producing optical structures on the transparent elements 6, it can be useful to polish one or both sides, for achieving an optical grade
20 surface, in particular a surface being particularly plane and having a particularly small surface roughness.

When, for obtaining an optics wafer, optical structures 5 are applied (e.g., by means of replication) to a semi-finished part, where concave menisci of the transparent material T are present, the replication can take place on
25 these menisci, wherein the amount of applied replication material might have to be adjusted accordingly. If a corresponding semi-finished part is polished, well-defined flat surfaces can be obtained, and less variation is

provided for subsequent replication steps. Thus, replication is likely to be carried out easier and/or can lead to a more stable (and reproduceable) process and to a possibly better precision.

- 5 The materials which are hardened, in particular cured, during a manufacturing process described anywhere above are typically polymer-based materials such as epoxy resins.

Due to manufacturing on wafer-level, most alignment steps are carried out on wafer-level making it possible to
10 achieve a very good alignment (in particular of members D and E with respect to passive optical component L) in a rather simple and very fast way. The overall manufacturing process is very fast and precise. Due to the wafer-scale manufacturing, only a very small number of production steps
15 is required for manufacturing a multitude of modules 1 and/or a multitude of optics members O.

The optics member O (and also the other addressed devices) can be useful in many applications, in particular where apertures are applied and/or where protection from light is
20 sought, and/or where mass production is necessary and/or where particularly small optical members (or passive optical components) are needed.

List of Reference Symbols

	1	device, opto-electronic module
5	2	device, wafer stack
	3	transparent region
	4	opening
	5	optical structure, lens element
	6	transparent element
10	7	solder ball
	8	precursor wafer
	9	printed circuit board
	10	device, electronic device, smart phone
	11	hole, opening
15	12	support layer
	13	support substrate
	b	blocking portion, non-transparent portion
	B	baffle member
20	BW	baffle wafer
	D	detector, light detector, photo diode
	E	light emitter, light-emitting diode
	L	passive optical component, lens member

O device, optics member
ow device, semi-finished part
ow' device, semi-finished part, "combined semi-finished
part"
5 OW device, optics wafer
P substrate
PW substrate wafer
S separation member
SW spacer wafer
10 t transparent portion
T transparent material

Patent Claims:

1. A method for manufacturing a device comprising at least one passive optical component, said method comprising
5 the step of

a) providing a wafer comprising at least one blocking portion and a multitude of transparent elements;

wherein each of said multitude of transparent elements is made of one or more materials substantially transparent for
10 light of at least a specific spectral range, referred to as transparent materials, and said at least one blocking portion is made of one or more materials substantially non-transparent for light of said specific spectral range, referred to as non-transparent materials.

15

2. The method according to claim 1, wherein a vertical extension of each of said multitude of transparent elements is at least approximately equal to a vertical extension of said at least one blocking portion.

20

3. The method according to claim 1 or claim 2, comprising the step of

d) manufacturing said wafer;

wherein step d) comprises the steps of

25 d1) providing a precursor wafer substantially made of said non-transparent material having openings in

places where said transparent elements are
supposed to be located;

d2) at least partially filling said openings with at
least one of said transparent materials.

5

4. The method according to claim 3, wherein step d2) is
carried out using a dispenser.

5. The method according to claim 3 or claim 4, comprising
10 the step of manufacturing said precursor wafer using
replication.

6. The method according to one of claims 1 to 5,
comprising the step of

15 c) manufacturing a wafer referred to as optics wafer,
comprising a multitude of passive optical components
comprising said at least one passive optical
component;

wherein step c) comprises the step of

20 c1) producing said multitude of passive optical
components by producing on each of said multitude
of transparent elements at least one optical
structure.

25 7. The method according to claim 6, wherein said at least
one optical structure comprises at least one lens element.

8. The method according to claim 6 or claim 7, said producing said optical structures is carried out using replication.

5

9. The method according to one of claims 6 to claim 8 , comprising the step of

e) preparing a wafer stack comprising said optics wafer and at least one additional wafer;

10 f) obtaining a multitude of separate modules each comprising at least one of said multitude of passive optical components, by separating said wafer stack.

10. A device comprising at least one optics member
15 comprising at least one transparent portion and at least one blocking portion, wherein said at least one transparent portion is made of one or more materials substantially transparent for light of at least a specific spectral range, referred to as transparent materials, and said at
20 least one blocking portion is made of one or more materials substantially non-transparent for light of said specific spectral range, referred to as non-transparent materials, wherein said transparent portion comprises at least one passive optical component, said at least one passive
25 optical component comprising a transparent element having two opposing at least approximately flat surfaces substantially perpendicular to a vertical direction, and,

attached to said transparent element, at least one optical structure.

11. The device according to claim 10, wherein said at
5 least one blocking portion is made of a hardened hardenable material.

12. The device according to claim 10 or claim 11, wherein
10 said transparent element is made of a hardened hardenable material.

13. The device according to one of claims 10 to 12,
wherein said at least one optical structure is made of a
hardened hardenable material.

15

14. The device according to one of claims 10 to 13,
wherein said at least one blocking portion and said at
least one optical structure are manufactured using
replication.

20

15. The device according to one of claims 10 to 14,
wherein said at least one optical structure comprises at
least one lens element.

25 16. The device according to one of claims 10 to 15,
wherein said passive optical component comprises at least

one optical structure attached to each of said opposing surfaces.

17. The device according to one of claims 10 to 16,
5 comprising an opto-electronic module in which said at least one optics member is comprised.

18. The device according to claim 17, wherein said device is said opto-electronic module.

10

19. The device according to claim 17 or claim 18, comprising a printed circuit board on which said opto-electronic module is mounted.

15 20. The device according to one of claims 10 to 19, wherein the device is a hand-held communication device.

21. The device according to one of claims 10 to 16, comprising a wafer referred to as optics wafer, said optics
20 wafer comprising a multitude of said optics members.

22. The device according to claims 21, wherein said device is said optics wafer.

25 23. The device according to claim 21, comprising a wafer stack in which said optics wafer is comprised.

24. The device according to claims 17, comprising a wafer stack in which a multitude of said opto-electronic modules is comprised.

5

25. The device according to claim 23 or claim 24, wherein said device is said wafer stack.